# **Specification of Thermoelectric Module**

### **TEHC1-04904**

### Description

The 49 couples, 25 mm  $\times$  25 mm size single module which is made of our high performance ingot to achieve superior cooling performance and 72° C or larger delta Tmax, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

#### Features

- High effective cooling and efficiency
- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly, RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

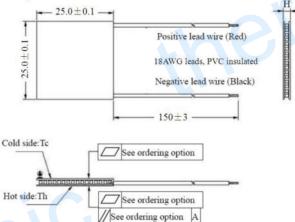
#### **Performance Specification Sheet**

### Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Temperature stabilizer
- Liquid cooling
- CPU cooler and scientific instrument
- Photonic and medical systems

Th (°C)	27	50	Hot side temperature at environment: dry air, N2	
DTmax (°C)	72	81	Temperature Difference between cold and hot side of the	
			module when cooling capacity is zero at cold side	
Umax (Voltage)	6.4	6.9	Voltage applied to the module at DTmax	
Imax (Amps)	4.6	4.6	DC current through the modules at DTmax	
QCmax (Watts)	18.7	20.5	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance (Ohms)	1.07	1.15	The module resistance is tested under AC	
Tolerance (%)	± 10		For thermal and electricity parameters	

### Geometric Characteristics Dimensions in millimeters



### **Manufacturing Options**

- 1. T100: BiSn (Tmelt=138°C)
- 2. T200: CuAgSn (Tmelt = 217°C)
- 3. T240: SbSn (Tmelt =  $240^{\circ}$ C)

#### C. Ceramics:

A. Solder:

- 1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)
- 2. Aluminum Nitride (AlN)

- B. Sealant:
- 1. NS: No sealing (Standard)
- 2. SS: Silicone sealant
- 3. EPS: Epoxy sealant

#### **D. Ceramics Surface Options:**

- 1. Blank ceramics (not metalized)
- 2. Metalized

### **Ordering Option**

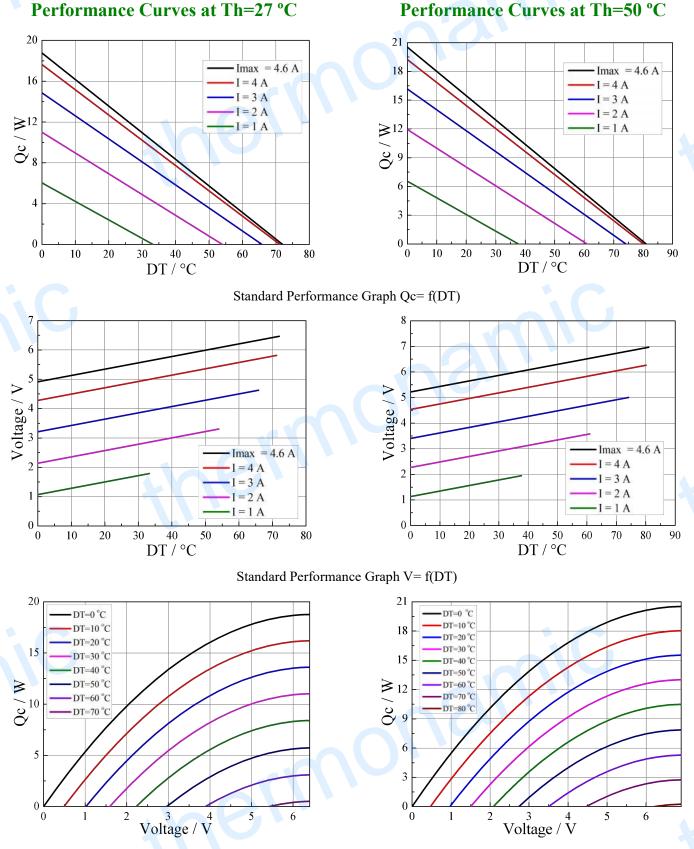
C ff	Thickness	Flatness/	Lead wire length (mm)	ТЕНС1-04904- Х-Х-Х-Х
Suffix	H / (mm)	Parallelism (mm)	Standard/Optional length	Ceramics Flatness/ Parallelism
TF	0:4.0±0.10	0:0.07/0.07	150±3/Specify	Sealant
TF	1:4.0±0.03	1:0.025/0.025	150±3/Specify	TEHC1-04904-T100-NS-TF01 -AlO
Eg. TI	F01: Thickness	4.0±0.10(mm) and F	T100: <u>BiSn(Tmelt=</u> 138°C) NS: No sealing <u>AlO</u> : Alumina white 96	

Creative technology with fine manufacturing processes provides you the reliable and quality products Tel: +86-791-88198288 Fax: +86-791-88198308 Email: <u>sales@thermonamic.com.cn</u> Web Site: www.thermonamic.com.cn

### Naming for the Module

# **Specification of Thermoelectric Module**

### **TEHC1-04904**



Standard Performance Graph Qc = f(V)

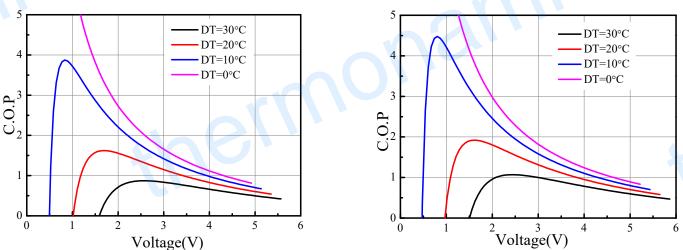
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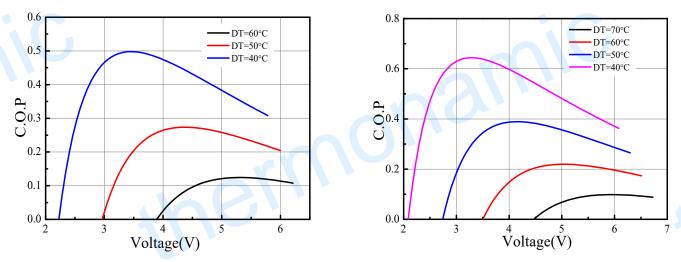
### **TEHC1-04904**



Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V × I).

### **Operation Cautions**

- Attach the cold side of module to the object to be cooled
- menc • Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I<sub>max</sub> or V<sub>max</sub>
- Work under DC